

## AO7800-VB Datasheet

# Dual N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
	$0.086$ at $V_{GS} = 4.5 \text{ V}$	2.6 <sup>a</sup>				
20	0.110 at V <sub>GS</sub> = 2.5 V	2.5 <sup>a</sup>	5.0 nC			
	0.180 at V <sub>GS</sub> = 1.8 V	2.3 <sup>a</sup>				

#### **FEATURES**

 Halogen-free According to IEC 61249-2-21 Definition

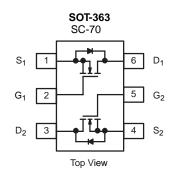


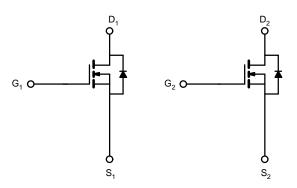
RoHS

- TrenchFET® Power MOSFET
- 100 % R<sub>a</sub> Tested
- Compliant to RoHS Directive 2002/95/EC

#### **APPLICATIONS**

• Load Switch for Portable Applications





ABSOLUTE MAXIMUM RATINGS	<b>S</b> (T <sub>A</sub> = 25 °C, unle	ss otherwise not	ed)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	20	V	
Gate-Source Voltage		V <sub>GS</sub>	± 12	v	
	T <sub>C</sub> = 25 °C		2.6 <sup>a</sup>		
Continuous Prois Compant (T. 450 °C)	T <sub>C</sub> = 70 °C		2.2 <sup>a</sup>		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	2.3 <sup>a, b, c</sup>		
	T <sub>A</sub> = 70 °C		1.8 <sup>b, c</sup>	А	
Pulsed Drain Current		I <sub>DM</sub>	8		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		2.3		
Continuous Source-Diam Diode Current	T <sub>A</sub> = 25 °C	l <sub>S</sub>	2.10 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		2.70		
Mayimum Dayyar Dissination	T <sub>C</sub> = 70 °C	Б	1.70	W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.5 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C		1.0 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	130	170	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	80	100	C/VV		

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.t = 5 s
- d. Maximum under steady state conditions is 220 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	·					ı
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	20			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 0504		20		>//00
$V_{GS(th)}$ Temperature Coefficient $\Delta V_{GS(th)}$		I <sub>D</sub> = 250 μA		- 2.3		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.5		2.0	V
Gate-Source Leakage		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 8 V			± 25	μА
	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			1	
Zana Cata Valta na Duain Coma di		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	4			Α
		$V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$		0.086		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 1 \text{ A}$		0.110		Ω
		V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 0.2 A		0.180		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 4 \text{ V}, I_{D} = 1.5 \text{ A}$		4		S
Dynamic <sup>b</sup>						
Tatal Cata Chausa	$Q_g$	$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 1.5 \text{ A}$		5.0		nC
Total Gate Charge				3.0		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 1.5 \text{ A}$		1.0		
Gate-Drain Charge	$Q_{gd}$			2.0		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	1.9	3.8	kΩ
Turn-On Delay Time	t <sub>d(on)</sub>			43	65	
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, R_1 = 8.3 \Omega$		80	120	1
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 1.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		480	720	-
Fall Time	t <sub>f</sub>			220	330	
Turn-on Delay Time	t <sub>d(on)</sub>			22	33	ns
Rise Time	tr	$V_{DD} = 10 \text{ V, R}_{L} = 8.3 \Omega$		46	70	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 1.2 \text{ A}, V_{GEN} = 8 \text{ V}, R_g = 1 \Omega$		645	968	
Fall Time	tr			215	323	
Drain-Source Body Diode Characteristic	s					
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C		2.6		
Pulse Diode Forward Current	I <sub>SM</sub>			4		A
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.2 A, V <sub>GS</sub> = 0 V		0.8	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			9	18	ns
Body Diode Reverse Recovery Charge Q <sub>rr</sub>		1 4 0 4 41/44 400 4/ 7 57 60		2	4	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 1.2 \text{ A, dI/dt} = 100 \text{ A/µs, T}_J = 25 °C$		5		
Reverse Recovery Rise Time	t <sub>b</sub>			4		ns

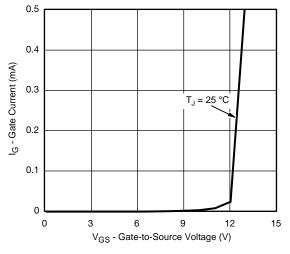
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

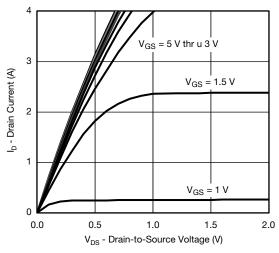
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



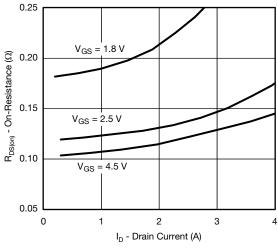
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



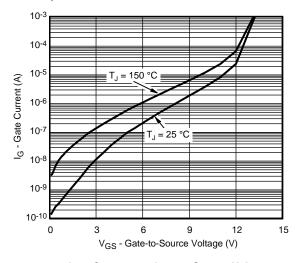
#### Gate Current vs. Gate-to-Source Voltage



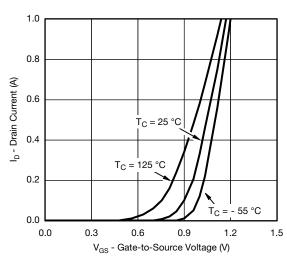
**Output Characteristics** 



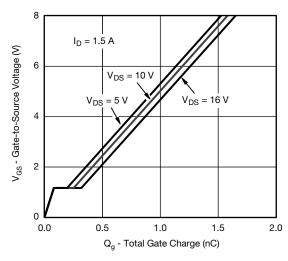
On-Resistance vs. Drain Current



Gate Current vs. Gate-to-Source Voltage



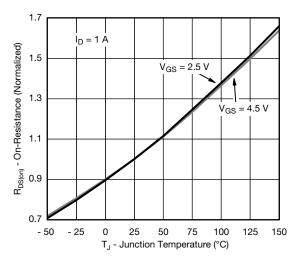
**Transfer Characteristics** 



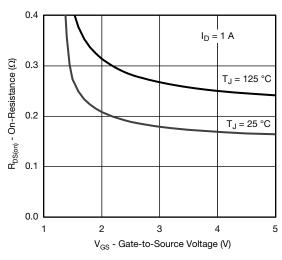
**Gate Charge** 



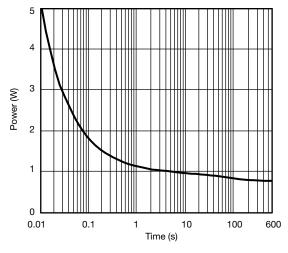
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



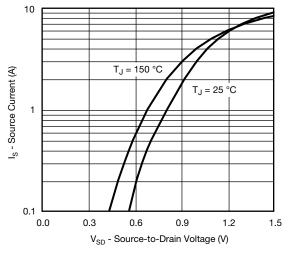
#### On-Resistance vs. Junction Temperature



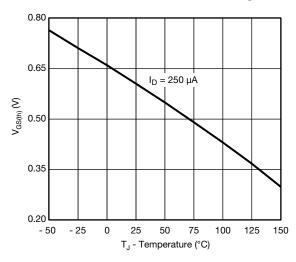
On-Resistance vs. Gate-to-Source Voltage



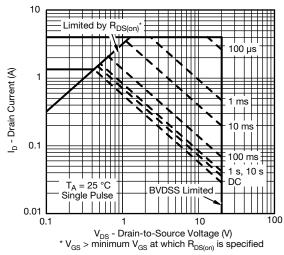
Single Pulse Power, Junction-to-Ambient



Source-Drain Diode Forward Voltage



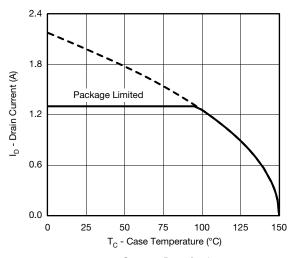
Threshold Voltage



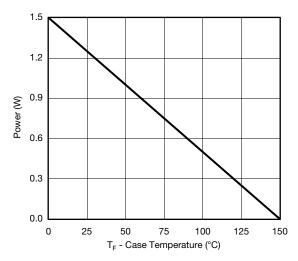
Safe Operating Area, Junction-to-Ambient



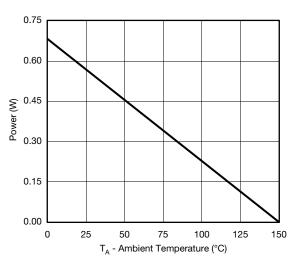
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### Current Derating\*





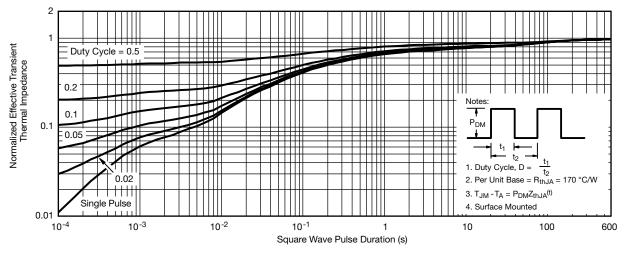


Power, Junction-to-Ambient

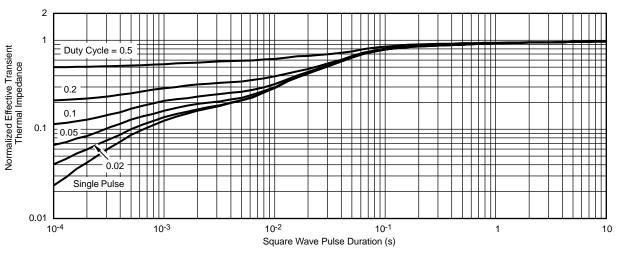
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



## TYPICAL CHARACTERISTICS (25 C, unless otherwise noted)



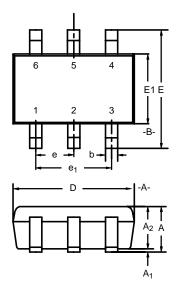
Normalized Thermal Transient Impedance, Junction-to-Ambient

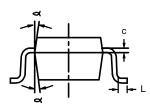


Normalized Thermal Transient Impedance, Junction-to-Foot



## SC-70: 6-LEADS





	MIL	LIMET	ERS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.90	-	1.10	0.035	_	0.043	
<b>A</b> <sub>1</sub>	-	-	0.10	-	_	0.004	
A <sub>2</sub>	0.80	_	1.00	0.031	_	0.039	
b	0.15	-	0.30	0.006	_	0.012	
С	0.10	_	0.25	0.004	_	0.010	
D	1.80	2.00	2.20	0.071	0.079	0.087	
Ε	1.80	2.10	2.40	0.071	0.083	0.094	
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053	
е	0.65BSC			0.026BSC			
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055	
L	0.10	0.20	0.30	0.004	0.008	0.012	
٦	7°Nom			7°Nom			



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